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Sheet 1 of 1

## **Complete if Known**

Application Number 10/017,403  
Filing Date December 14, 2001  
First Named Inventor Frederick GIACOBBE  
Group Art Unit 2857  
Examiner Name To Be Assigned  
Attorney Docket Number 25184-P029US

## **U.S. PATENT DOCUMENTS**

Examiner Initials	Cite No. <sup>1</sup>	U.S. Patent Document		Name of Patentee or Applicant of cited document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear
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## **FOREIGN PATENT DOCUMENTS**

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Examiner Initials	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the Item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), Publisher, city, and/or country where published.	T <sup>2</sup>
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